

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

|                      |   |                                      |
|----------------------|---|--------------------------------------|
| 1.1 Company          |  | STMicroelectronics International N.V |
| 1.2 PCN No.          | POWER AND DISCRETE PRODUCTS/24/14809  |                                      |
| 1.3 Title of PCN     | Mold Compound replacement for industrial device                                   |                                      |
| 1.4 Product Category | SiC   |                                      |
| 1.5 Issue date       | 2024-06-17  |                                      |

**2. PCN Team**

|                           |                   |
|---------------------------|-------------------|
| 2.1 Contact supplier      |                   |
| 2.1.1 Name                | PIKE EMMA         |
| 2.1.2 Phone               | +44 1628896111    |
| 2.1.3 Email               | emma.pike@st.com  |
| 2.2 Change responsibility |                   |
| 2.2.1 Product Manager     | Riccardo NICOLoso |
| 2.1.2 Marketing Manager   | Antonino GAITO    |
| 2.1.3 Quality Manager     | Vincenzo MILITANO |

**3. Change**

|              |   |                            |
|--------------|---|----------------------------|
| 3.1 Category | 3.2 Type of change  | 3.3 Manufacturing Location |
| Materials    | Direct Material: Mold compound - Chemistry (raw material) | Nantong - China            |

**4. Description of change**

|   |                               |                      |
|---|-------------------------------|----------------------|
|   | Old                           | New                  |
| 4.1 Description   | Resin EMC: Kyocera KEG-300S-1 | Resin HHCK EMG-400-C |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | Processability                |                      |

**5. Reason / motivation for change**

|                      |                                      |
|----------------------|--------------------------------------|
| 5.1 Motivation       | KYOCERA KEG-300S-1 out of production |
| 5.2 Customer Benefit | SERVICE CONTINUITY                   |

**6. Marking of parts / traceability of change**

|                 |              |
|-----------------|--------------|
| 6.1 Description | by QA number |
|-----------------|--------------|

**7. Timing / schedule**

|                                     |              |
|-------------------------------------|--------------|
| 7.1 Date of qualification results   | 2024-06-06   |
| 7.2 Intended start of delivery      | 2024-09-11   |
| 7.3 Qualification sample available? | Upon Request |

**8. Qualification / Validation**

|  |   |            |            |
|--|---|------------|------------|
| 8.1 Description                                    | 14809 RERPTD24013_1.0_SiC family in TO247-LL TFME with resin EMG400. rev3.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)  | Issue Date | 2024-06-17 |

**9. Attachments (additional documentations)**

14809 Public product.pdf  
 14809 14809.pdf  
 14809 RERPTD24013\_1.0\_SiC family in TO247-LL TFME with resin EMG400. rev3.pdf

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | SCTWA35N65G2V-4         |                          |
|                         | SCTWA70N120G2V-4        |                          |
|                         | SCTWA90N65G2V           |                          |
| 3764236                 | SCTWA90N65G2V-4         |                          |

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